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PTO/SB/05 (4/98)
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UTILITY PATENT APPLICATION TRANSMITTAL <small>(Only for new nonprovisional applications under 37 C.F.R. § 1.53(b))</small>	Attorney Docket No.	MI22-1376
	First Inventor or Application Identifier	Kevin J. Torek et al.
	Title	Methods of Removing at Least Some of A Material from....
	Express Mail Label No.	465686385

APPLICATION ELEMENTS <small>See MPEP chapter 600 concerning utility patent application contents.</small>	ADDRESS TO: Assistant Commissioner for Patents Box Patent Application Washington, DC 20231
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1. <input checked="" type="checkbox"/> * Fee Transmittal Form (e.g., PTO/SB/17) <small>(Submit an original and a duplicate for fee processing)</small>	5. <input type="checkbox"/> Microfiche Computer Program (Appendix)
2. <input checked="" type="checkbox"/> Specification <small>(preferred arrangement set forth below)</small> [Total Pages] 20 1 includes title page - Descriptive title of the invention - Cross References to Related Applications - Statement Regarding Fed sponsored R & D - Reference to Microfiche Appendix - Background of the invention - Brief Summary of the invention - Brief Description of the Drawings (if filed) - Detailed Description - Claim(s) - Abstract of the Disclosure	6. Nucleotide and/or Amino Acid Sequence Submission <small>(if applicable, all necessary)</small> a. <input type="checkbox"/> Computer Readable Copy b. <input type="checkbox"/> Paper Copy (identical to computer copy) c. <input type="checkbox"/> Statement verifying identity of above copies
3. <input checked="" type="checkbox"/> Drawing(s) (35 U.S.C. 113) [Total Sheets] 2 1	
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ACCOMPANYING APPLICATION PARTS	
7. <input type="checkbox"/> Assignment Papers (cover sheet & document(s))	
8. <input type="checkbox"/> 37 C.F.R. § 3.73(b) Statement <input type="checkbox"/> Power of Attorney <small>(when there is an assignee)</small>	
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Small Entity payments must be supported by a small entity statement, otherwise large entity fees must be paid. See Forms PTO/SB/09-12.**TOTAL AMOUNT OF PAYMENT** (\$1,038.00)**Complete if Known**

Application Number	Filed Herewith
Filing Date	
First Named Inventor	Kevin J. Torek et al.
Examiner Name	
Group / Art Unit	
Attorney Docket No.	MI22-1376

METHOD OF PAYMENT (check one)

- 1.
- ☒
- The Commissioner is hereby authorized to charge indicated fees and credit any over payments to:

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FEE CALCULATION**1. BASIC FILING FEE**

Large Fee Code	Entity Fee (\$)	Small Fee Code	Entity Fee (\$)	Fee Description	Fee Paid
101	760	201	380	Utility filing fee	690.00
106	310	206	155	Design filing fee	
107	480	207	240	Plant filing fee	
108	760	208	380	Reissue filing fee	
114	150	214	75	Provisional filing fee	

SUBTOTAL (1) (\$ 690.00)**2. EXTRA CLAIM FEES**

Total Claims	Extra Claims	Fee from below	Fee Paid
35	-20** = 15	18	270.00
4	-3** = 1	78.00	78.00
			0.00

**or number previously paid, if greater; For Reissues, see below

Large Fee Code	Entity Fee (\$)	Small Fee Code	Entity Fee (\$)	Fee Description
103	18	203	9	Claims in excess of 20
102	78	202	39	Independent claims in excess of 3
104	260	204	130	Multiple dependent claim, if not paid
109	78	209	39	** Reissue independent claims over original patent
110	18	210	9	** Reissue claims in excess of 20 and over original patent

SUBTOTAL (2) (\$ 348.00)**FEE CALCULATION (continued)****3. ADDITIONAL FEES**

Large Fee Code	Entity Fee (\$)	Small Fee Code	Entity Fee (\$)	Fee Description	Fee Paid
105	130	205	65	Surcharge - late filing fee or oath	0.00
127	50	227	25	Surcharge - late provisional filing fee or cover sheet.	0.00
139	130	139	130	Non-English specification	0.00
147	2,520	147	2,520	For filing a request for reexamination	0.00
112	920*	112	920*	Requesting publication of SIR prior to Examiner action	0.00
113	1,840*	113	1,840*	Requesting publication of SIR after Examiner action	0.00
115	110	215	55	Extension for reply within first month	0.00
116	380	216	190	Extension for reply within second month	0.00
117	870	217	435	Extension for reply within third month	0.00
118	1,360	218	680	Extension for reply within fourth month	0.00
128	1,850	228	925	Extension for reply within fifth month	0.00
119	300	219	150	Notice of Appeal	0.00
120	300	220	150	Filing a brief in support of an appeal	0.00
121	260	221	130	Request for oral hearing	0.00
138	1,510	138	1,510	Petition to institute a public use proceeding	0.00
140	110	240	55	Petition to revive - unavoidable	0.00
141	1,210	241	605	Petition to revive - unintentional	0.00
142	1,210	242	605	Utility issue fee (or reissue)	0.00
143	430	243	215	Design issue fee	0.00
144	580	244	290	Plant issue fee	0.00
122	130	122	130	Petitions to the Commissioner	0.00
123	50	123	50	Petitions related to provisional applications	0.00
126	240	126	240	Submission of Information Disclosure Stmt	0.00
581	40	581	40	Recording each patent assignment per property (times number of properties)	0.00
146	760	246	380	Filing a submission after final rejection (37 CFR 1.129(a))	0.00
149	760	249	380	For each additional invention to be examined (37 CFR 1.129(b))	0.00
Other fee (specify) _____					0.00
Other fee (specify) _____					0.00

*Reduced by Basic Filing Fee Paid

SUBTOTAL (3) (\$ 0.00)**SUBMITTED BY**Typed or Printed Name **David G. Latwesen, Ph.D.**Signature Date **8/31/00****Complete (if applicable)**Reg. Number **38,533**

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICATION FOR LETTERS PATENT

* * * * *

**Methods of Removing at Least Some Of A
Material from A Semiconductor Substrate**

* * * * *

INVENTORS

Kevin J. Torek
Garo J. Derderian

ATTORNEY'S DOCKET NO. MI22-1376

1 Methods of Removing at Least Some Of A Material from
2 A Semiconductor Substrate

3 TECHNICAL FIELD

4 The invention pertains to methods of forming and utilizing ozone
5 to remove at least some of a material from a semiconductor substrate.
6 In particular applications, the invention pertains to methods of utilizing
7 organic material vapors in combination with ozone to remove materials
8 from semiconductor substrates.

9
10 BACKGROUND OF THE INVENTION

11 It is common to utilize ozone for removing materials from over
12 semiconductor substrates during semiconductor device fabrication. For
13 instance, ozone can be utilized for removing photoresist and other
14 organic materials. The ozone is typically generated proximate to, or
15 within, a reaction chamber. The semiconductor substrate is provided
16 within the reaction chamber, and the ozone is contacted with the
17 material which is to be removed.

18 Ozone can be utilized for removing organic materials, such as, for
19 example, photoresist, in that the ozone can oxidize the organic material
20 and thereby convert the organic material to a form which is more readily
21 removed from over a semiconductor substrate than was the organic
22 material prior to oxidation.

1 A method of forming ozone is to feed a diatomic oxygen (O_2)
2 containing feed gas into an ozone generator. The feed gas is generally
3 about 99.9% O_2 (by volume), with the remaining 0.1% of the feed gas
4 comprising mostly nitrogen (N_2). Occasionally, additional nitrogen may
5 be spiked into the feed gas to raise a concentration of nitrogen up to
6 about 5%. A reason for utilizing the relatively low purity oxygen as a
7 feed gas for generating ozone is that it can be cheaper than higher
8 purity oxygen. Another reason is that there can be a reduced risk of
9 flame or explosion in utilizing a lower purity oxygen, relative to that
10 which would exist in utilizing a higher purity oxygen.

11 The invention encompasses new methods of forming and utilizing
12 ozone in removing materials from over semiconductor substrates.

13 14 SUMMARY OF THE INVENTION

15 The invention encompasses a method of removing at least some of
16 a material from a semiconductor substrate. A feed gas is fed through
17 an ozone generator to generate ozone. The feed gas comprises at least
18 99.999% O_2 (by volume). The ozone, or a fragment of the ozone, is
19 contacted with a material on a semiconductor substrate to remove at
20 least some of the material from the semiconductor substrate.

21 In another aspect, the invention encompasses another method of
22 removing at least some of a material from a semiconductor substrate.
23 A mixture of ozone and organic solvent vapors is formed in a reaction

1 chamber. At least some of the ozone and solvent vapors are contacted
2 with a material on a semiconductor substrate to remove at least some
3 of the material from the semiconductor substrate.
4

5 **BRIEF DESCRIPTION OF THE DRAWINGS**

6 Preferred embodiments of the invention are described below with
7 reference to the following accompanying drawings.

8 Fig. 1 is a diagrammatic, cross-sectional view of a reaction chamber
9 utilized in accordance with a method of the present invention.

10 Fig. 2 is a diagrammatic, cross-sectional, fragmentary view of a
11 semiconductor wafer fragment at a preliminary processing step of a
12 method of the present invention.

13 Fig. 3 is a view of the Fig. 2 wafer fragment shown at a
14 processing step subsequent to that of Fig. 2.
15

16 **DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS**

17 This disclosure of the invention is submitted in furtherance of the
18 constitutional purposes of the U.S. Patent Laws "to promote the progress
19 of science and useful arts" (Article 1, Section 8).

20 Methodology encompassed by the present invention is described
21 with reference to Figs. 1-3. Referring initially to Fig. 1, an
22 apparatus 10 is diagrammatically illustrated. Apparatus 10 comprises a
23

1 reaction chamber 12 having a semiconductor wafer support 14 therein.
2 A semiconductor wafer 16 is shown on support 14.

3 An ozone generator 18 is shown mounted relative to chamber 12
4 such that ozone 20 formed within generator 18 is expelled into
5 chamber 12. An exemplary ozone generator is an ASTEX™ 8200, which
6 is manufactured by Applied Science and Technology, of 3500 Cabot Rd,
7 Woburn, Massachusetts. It is to be understood that ozone generator 18
8 can be mounted outside of chamber 12, and ozone flowed from generator
9 18 into chamber 12. It is also to be understood that ozone generator
10 18 could be mounted such that it is fully enclosed within chamber 12.
11 Further, it is to be understood that ozone generator 18 can be mounted
12 above wafer 16, as shown, or can be mounted in other orientations
13 relative to wafer 16.

14 A feed gas source 22 is provided externally of chamber 12, and
15 a feed gas 24 is flowed from source 22 to ozone generator 18. Feed
16 gas 24 comprises O₂, and in contrast to the prior art preferably
17 comprises at least 99.999% O₂ (by volume). Feed gas 24 is flowed into
18 ozone generator 18 to form ozone 20. An advantage of utilizing a feed
19 gas with a higher purity of oxygen than the prior art is that such
20 reduces a concentration of nitrogen within the feed gas. In accordance
21 with one aspect of the invention, it is recognized that nitrogen can be
22 converted to various nitrous oxides (NO_x) upon being passed with oxygen
23 through an ozone generator. The nitrous oxides can be corrosive and

1 otherwise damaging to integrated circuitry exposed to the nitrous oxides.
2 Further, the nitrous oxides can form various acids (such as, for example,
3 HNO_3) which can be corrosive to various integrated circuitry materials,
4 such as, for example, aluminum oxide (Al_2O_3). Accordingly, one aspect
5 of the invention encompasses utilization of a higher purity oxygen in an
6 ozone-generating feed gas than that which is utilized in the prior art.
7 A related aspect of the invention is that such utilizes an ozone-
8 generating feed gas having less nitrogen than prior art feed gases.
9 Preferably, the ozone-generating feed gas 24 comprises less than or equal
10 to 0.001% N_2 (by volume).

11 Semiconductor substrate 16 comprises an upper layer 17.
12 Semiconductor substrate 16 can comprise, for example, monocrystalline
13 silicon lightly-doped with a background p-type dopant. To aid in
14 interpretation of the claims that follow, the terms "semiconductive
15 substrate" and "semiconductor substrate" are defined to mean any
16 construction comprising semiconductive material, including, but not limited
17 to, bulk semiconductive materials such as a semiconductive wafer (either
18 alone or in assemblies comprising other materials thereon), and
19 semiconductive material layers (either alone or in assemblies comprising
20 other materials). The term "substrate" refers to any supporting
21 structure, including, but not limited to, the semiconductive substrates
22 described above. Upper layer 17 can comprise, for example, aluminum
23

oxide (Al_2O_3), platinum, or other materials associated with fabrication of integrated circuitry.

A layer 19 is over upper layer 17 of semiconductor substrate 16, and comprises a material which is to be removed. Layer 19 can comprise, for example, photoresist, such as, for example, a so-called I-line photoresist (typically a novolac resin), or a deep ultraviolet resist. Alternatively, layer 19 can comprise other organic materials.

Ozone 20 is utilized to remove at least some of layer 19 from over semiconductor substrate 16. In other words, the ozone is utilized to remove a material defined by layer 19 from over the upper layer 17 of semiconductor substrate 16.

In one aspect, ozone 20 flows to material 19 to react with the material and form a product which can be removed from over semiconductor substrate 16. For instance, ozone 20 can oxidize an organic material 19 to form a relatively volatile material which can be swept from over layer 17 by flow of gases through reaction chamber 12.

In another aspect, ozone 20 can be broken into reactive fragments which contact material 19 and react with the material to form a product which can be removed from over layer 17. In the shown embodiment, an ultraviolet light source 30 is provided proximate reaction chamber 12 and adjacent a window 32 which extends through a wall of reaction chamber 12. Ultraviolet light generated by source 30 passes through window 32 into chamber 12. The ultraviolet light can then impact

1 ozone 20 within chamber 12 to cause the ozone to break into reactive
2 fragments. Such reactive fragments can comprise, for example, atomic
3 oxygen. The fragments formed from the ozone can also comprise O₂.
4 In embodiments in which ozone 20 is exposed to ultraviolet light prior
5 to contact of the ozone or fragments thereof with material 19, such
6 exposure preferably occurs proximate layer 19. In such context, the term
7 "proximate" means that the exposure occurs within one foot of layer 19.
8 Such can alleviate losses of the reactive species formed by the exposure
9 prior to interaction of the reactive species with layer 19. In particular
10 aspects of the invention, the ultraviolet light can be shined onto a
11 surface of layer 19 while the surface is exposed to ozone.

12 The apparatus 10 of Fig. 1 further comprises a reservoir 50
13 comprising a volatile material 52. Reservoir 50 is on a reservoir
14 holder 54 which can comprise a heater. In operation, material 52 is
15 volatilized from reservoir 50 to form vapor within reaction chamber 12
16 which can enhance removal of material 19 by ozone 20. Volatile
17 material 52 can comprise, for example, water, and accordingly the vapor
18 formed within the reaction chamber 12 will be water vapor.
19 Alternatively, volatile material 52 could comprise an organic solvent such
20 as, for example, one or more of cyclohexanone, acetone, or propylene
21 glycol methylether acetate (PGMEA). In particular embodiments, the
22 solvent can consist essentially of, or consist of, acetone. In other
23 embodiments, the solvent can consist essentially of, or consist of,

1 cyclohexanone. In yet other embodiments, the solvent can consist
2 essentially of, or consist of, a mixture of cyclohexanone and PGMEA.
3 A particular solvent can comprise a mixture of 60% cyclohexanone and
4 40% PGMEA. An alternative solvent is propylene glycol. Although the
5 solvents described above would be liquid materials, it is to be understood
6 that reservoir 50 could also comprise a volatile solid material.

7 If the material 52 is volatile at a temperature within reactor 12,
8 vapors will be formed from material 52 without additional heating of the
9 material. Alternatively, if material 52 is not volatile at the temperature
10 of reaction chamber 12, or if it desired to enhance volatilization of
11 material 52, the material can be heated by, for example, a heater within
12 support 54.

13 If material 52 comprises a volatile organic material, then the
14 vapors formed from material 52 will be volatile organic solvent vapors.
15 It is to be understood that within the context of this document the term
16 "solvent vapor" refers to a vapor formed from a volatile organic
17 material, and not to any volatile organic materials formed by degradation
18 of layer 19 within chamber 12. If volatile solvent vapors are utilized in
19 conjunction with the very pure oxygen described above, it is preferred
20 that flames and sparks be kept out of the reaction chamber to alleviate
21 a risk of fire or explosion.

22 Although reservoir 50 is shown provided within chamber 12, it is
23 to be understood that the invention encompasses other embodiments

1 wherein reservoir 50 is provided outside of chamber 12, and wherein
2 solvent vapors are flowed into chamber 12 from the external reservoir.
3 Also, the invention encompasses embodiments wherein vapors are
4 provided in a gas source external of chamber 12 (such as, for example,
5 a tank of gas), and piped into chamber 12.

6 Organic solvent vapors are found to assist in removal of organic
7 materials 19 (such as, for example, photoresist) from over semiconductor
8 substrates. A possible mechanism is that the vapors may "wet" or
9 otherwise improve susceptibility of an organic material 19 to ozone or
10 reactive fragments formed from ozone. Such mechanism is provided to
11 assist in understanding the present invention, and is not to limit the
12 claims except to the extent that the mechanism is expressly recited within
13 a claim.

14 Figs. 2 and 3 illustrate enlarged views of the semiconductor
15 substrate 16 at processing steps of a method of the present invention.
16 Fig. 2 illustrates semiconductor substrate 16 having material 19 thereover.
17 Specifically, material 19 is over a layer 17. As discussed above, layer 19
18 can comprise an organic material such as, for example, photoresist.
19 Layer 17 can comprise an inorganic material such as, for example,
20 aluminum oxide or platinum.

21 Referring to Fig. 3, semiconductor substrate 16 is illustrated after
22 material 19 has been removed from over layer 17. Such removal can be
23 accomplished by the processing described above with reference to Fig. 1,

1 wherein ozone (or a reactive fragment generated from ozone) is
2 contacted with material 19 to remove material 19. It is noted that some
3 of layer 17 can be exposed to the ozone, or ozone fragments, during
4 removal of material 19. In accordance with an embodiment of the
5 present invention, the ozone preferably will be formed from an oxygen
6 feed material that comprised less than 0.001% nitrogen. Accordingly,
7 any concentration of nitrous oxides or reactive products formed from
8 nitrous oxides will be lower in methods of the present invention than in
9 prior art processes. Accordingly, if layer 17 comprises aluminum oxide,
10 platinum, or other materials which can be etched or otherwise corroded
11 by nitrous oxide or products thereof, methods of the present invention
12 can alleviate such corrosion relative to prior art methods.

13 In compliance with the statute, the invention has been described
14 in language more or less specific as to structural and methodical
15 features. It is to be understood, however, that the invention is not
16 limited to the specific features shown and described, since the means
17 herein disclosed comprise preferred forms of putting the invention into
18 effect. The invention is, therefore, claimed in any of its forms or
19 modifications within the proper scope of the appended claims
20 appropriately interpreted in accordance with the doctrine of equivalents.
21
22
23

1 **CLAIMS:**

2 1. A method of removing at least some of a material from a
3 semiconductor substrate, comprising:

4 feeding a feed gas through an ozone generator to generate ozone
5 from the feed gas; the feed gas comprising at least 99.999% O₂ (by
6 volume); and

7 contacting the ozone or a fragment of the ozone with a material
8 on a semiconductor substrate to remove at least some of the material
9 from the semiconductor substrate.

10
11 2. The method of claim 1 further comprising irradiating at least
12 some of the ozone with ultraviolet light prior to the contacting.

13
14 3. The method of claim 1 further comprising irradiating at least
15 some of the ozone with ultraviolet light proximate the material.

16
17 4. The method of claim 1 wherein the material on the
18 semiconductor substrate is photoresist.

19
20 5. The method of claim 1 further comprising mixing the ozone
21 with water vapor prior to the contacting.

1 6. The method of claim 1 further comprising mixing the ozone
2 with an organic solvent vapor prior to the contacting.

3
4 7. A method of removing at least some of a material from a
5 semiconductor substrate, comprising:

6 feeding a feed gas through an ozone generator to generate ozone
7 from the feed gas; the feed gas comprising O₂ and less than or equal
8 to 0.001% N₂ (by volume); and

9 contacting the ozone or a fragment of the ozone with a material
10 on a semiconductor substrate to remove at least some of the material
11 from the semiconductor substrate.

12
13 8. The method of claim 7 further comprising irradiating at least
14 some of the ozone with ultraviolet light prior to the contacting.

15
16 9. The method of claim 7 wherein the material on the
17 semiconductor substrate is photoresist.

18
19 10. The method of claim 7 further comprising mixing the ozone
20 with water vapor prior to the contacting.

1 11. The method of claim 7 further comprising mixing the ozone
2 with an organic solvent vapor prior to the contacting.

3
4 12. A method of removing at least some of a material from a
5 semiconductor substrate, comprising:

6 forming a mixture of ozone and organic solvent vapors in a
7 reaction chamber; and

8 contacting at least some of the ozone and solvent vapors with a
9 material on a semiconductor substrate to remove at least some of the
10 material from the semiconductor substrate.

11
12 13. The method of claim 12 wherein the material on the
13 semiconductor substrate is photoresist.

14
15 14. The method of claim 12 wherein the material on the
16 semiconductor substrate is photoresist; wherein the semiconductor
17 substrate comprises Al_2O_3 ; and further comprising exposing at least some
18 of the Al_2O_3 to the ozone during the contacting.

1 15. The method of claim 12 wherein the material on the
2 semiconductor substrate is photoresist; wherein the semiconductor
3 substrate comprises platinum; and further comprising exposing at least
4 some of the platinum to the ozone during the contacting.

5
6 16. The method of claim 12 further comprising providing a
7 reservoir of volatile organic solvent within the reaction chamber and
8 forming the solvent vapors from the volatile organic solvent.

9
10 17. The method of claim 16 wherein the volatile organic solvent
11 is a liquid.

12
13 18. The method of claim 16 wherein the volatile organic solvent
14 comprises acetone.

15
16 19. The method of claim 16 wherein the volatile organic solvent
17 consists essentially of acetone.

18
19 20. The method of claim 16 wherein the volatile organic solvent
20 comprises cyclohexanone.

1 21. The method of claim 16 wherein the volatile organic solvent
2 consists essentially of cyclohexanone.

3
4 22. The method of claim 16 wherein the volatile organic solvent
5 comprises a mixture of cyclohexanone and PGMEA.

6
7 23. The method of claim 16 wherein the volatile organic solvent
8 comprises propylene glycol.

9
10 24. The method of claim 12 further comprising providing a
11 reservoir of volatile organic solvent within the reaction chamber and
12 heating the volatile organic solvent to form the solvent vapors from the
13 volatile organic solvent.

1 25. A method of removing at least some of a material from a
2 semiconductor substrate, comprising:

3 forming a mixture of ozone and organic solvent vapors in a
4 reaction chamber;

5 irradiating at least some of the ozone with ultraviolet light to form
6 ozone fragments from the ozone; and

7 contacting at least some of the ozone fragments and solvent vapors
8 with a material on a semiconductor substrate to remove at least some
9 of the material from the semiconductor substrate.

10
11 26. The method of claim 25 wherein the material on the
12 semiconductor substrate is photoresist.

13
14 27. The method of claim 25 further comprising providing a
15 reservoir of volatile organic solvent within the reaction chamber and
16 forming the solvent vapors from the volatile organic solvent.

17
18 28. The method of claim 27 wherein the volatile organic solvent
19 is a liquid.

20
21 29. The method of claim 27 wherein the volatile organic solvent
22 comprises acetone.

1 30. The method of claim 27 wherein the volatile organic solvent
2 comprises cyclohexanone.

3
4 31. The method of claim 27 wherein the volatile organic solvent
5 comprises a mixture of cyclohexanone and PGMEA.

6
7 32. The method of claim 27 wherein the volatile organic solvent
8 comprises propylene glycol.

9
10 33. The method of claim 25 further comprising providing a
11 reservoir of volatile organic solvent within the reaction chamber and
12 heating the volatile organic solvent to form the solvent vapors from the
13 volatile organic solvent.

14
15 34. The method of claim 25 wherein the material on the
16 semiconductor substrate is photoresist; wherein the semiconductor
17 substrate comprises Al_2O_3 ; and further comprising exposing at least some
18 of the Al_2O_3 to the ozone fragments during the contacting.

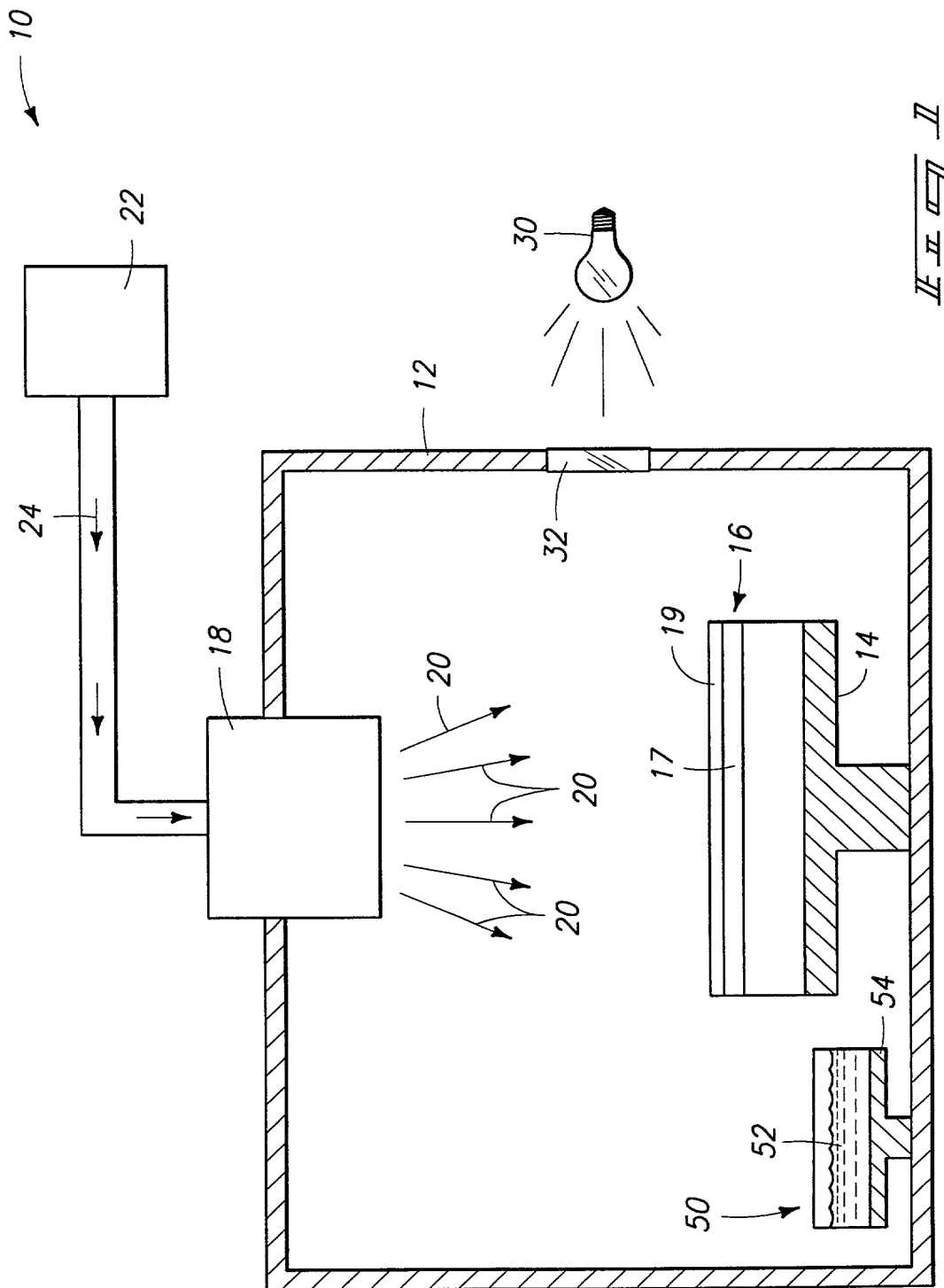
1 35. The method of claim 25 wherein the material on the
2 semiconductor substrate is photoresist; wherein the semiconductor
3 substrate comprises platinum; and further comprising exposing at least
4 some of the platinum to the ozone fragments during the contacting. .
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1 **ABSTRACT OF THE DISCLOSURE**

2 The invention encompasses a method of removing at least some of
3 a material from a semiconductor substrate. A feed gas is fed through
4 an ozone generator to generate ozone. The feed gas comprises at least
5 99.999% O₂ (by volume). The ozone, or a fragment of the ozone, is
6 contacted with a material on a semiconductor substrate to remove at
7 least some of the material from the semiconductor substrate. The
8 invention also encompasses another method of removing at least some of
9 a material from a semiconductor substrate. A mixture of ozone and
10 organic solvent vapors is formed in a reaction chamber. At least some
11 of the ozone and solvent vapors are contacted with a material on a
12 semiconductor substrate to remove at least some of the material from
13 the semiconductor substrate.

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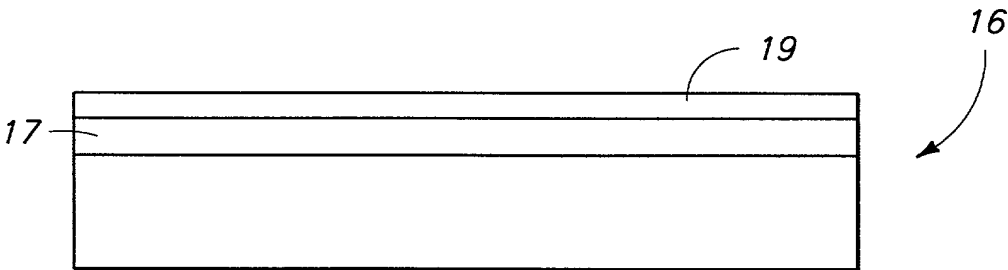


FIG. 2

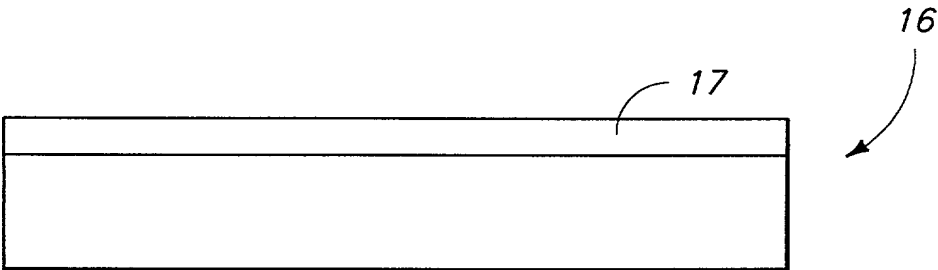


FIG. 3

DECLARATION OF JOINT INVENTORS FOR PATENT APPLICATION

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled: Methods of Removing at Least Some of a Material from a Semiconductor Substrate, the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations §1.56.

PRIOR FOREIGN APPLICATIONS:

I hereby state that no applications for foreign patents or inventor's certificates have been filed prior to the date of execution of this declaration.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so

made are punishable by fine or imprisonment, or both, under
Section 1001 of Title 18 of the United States Code and that such willful
false statement may jeopardize the validity of the application or any
patent issued therefrom.

* * * * *

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